

<b>Form 1449 (Modified)</b>  <b>Information Disclosure Statement By Applicant</b>  (Use Several Sheets if Necessary)	Atty Docket No.	Application No.:
	NSC1P296/P05887	NEW
	Applicant:	
	Soon et al.	
Filing Date	Group	
HEREWITH	UNASSIGNED	

### U.S. Patent and Published Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
Qh	A1	5,328,079	07/12/1994	Mathew et al.	/	/	
	A2	5,408,127	4/18/95	Mostafazadeh	/	/	
	A3	4,818,895	4/4/89	Kaufman	/	/	
	A4	5,735,030	4/7/98	Orcutt	/	/	
	A5	6,399,421	06/02	Han et al.	/	/	
	A6	5,463,253	10/95	Waki et al.	/	/	
	A7	6,437,429	08/02	Wu et al.	/	/	
	A8	6,118,184	09/00	Ishio et al.	/	/	
	A9	5,471,369	11/95	Honda et al.	/	/	
	A10	2002/0137327	09/02	Arakawa	/	/	
	A11	5,545,922	08/96	Golwalker et al.	/	/	
Qh	A12	6,353,265	03/02	Michii	/	/	

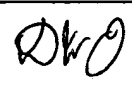
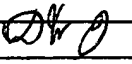

### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
Qh	B1	WO02/08257	10/17/02	WIPO	/	/		
Qh	B2	EP0753891	1/15/97	EPO	/	/		

### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
Qh	C1	John Barber, "Plastic Packaging and the Effects of Surface Mount Soldering Techniques," Microchip Technology, Inc., 12 pages, 1995
Qh	C2	Lai et al., Nordic Electronic Packaging Guideline, Chapter A, printed from: <a href="http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm">http://www.extra.ivf.se/mgl/A-WireBonding/ChapterA.htm</a> , on March 16, 2004, 25 Pages
Qh	C3	Prof. Daniel F. Baldwin, "Fundamentals of IC Assembly," McGraw-Hill, Chapter. 9, pages 342-353, 2001
Qh	C4	Semiconductor Packaging Assembly Technology, printed from <a href="http://www.national.com">www.national.com</a> , 8 pages, 1999

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	C5	Nakanishi et al., "Development of High Density Memory IC Package by Stacking IC Chips," Abstract No. XP000624986, IEEE, Vol. Conf. 45, Pages 634-640 (1995)
	C6	Patent Abstract of Japan, Pub No. 63219131, Pub Date 9/12/88, 2 Pages
Examiner 		Date Considered 1/11/05

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.